



- 100% Rosin coreless !!
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Model: BST-706
 Reflow Temp: 138 °C
 Solderability: 500 g
 Alloy: Sn99% Cu0.7% Ag0.3%



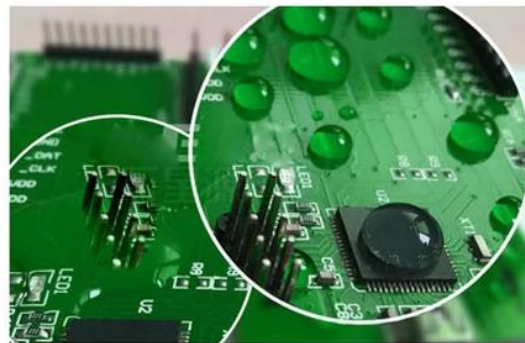
500g
Low residue / Rapid welding / lead free / Solder spot bright

Product Usage

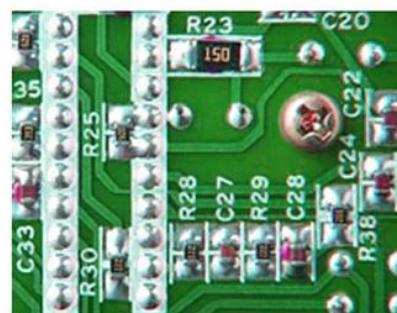
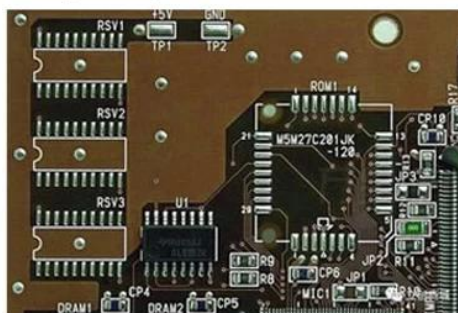


MODEL	BST-706
SHELF LIFE	6 months
INGREDIENT	Sn42/Bi58
WEIGHT	500g
MELTING POINT	138°C

Having a large insulation resistance does not corrode the PCB, and the requirements for no-cleaning can be achieved.



High impedance, full and bright solder, low residue



Welding requirements for a wide range of products



TESTING EFFECT

UNIFORM SOLDER JOINT
MEDIUM TEMPERATURE MELTING POINT



PRODUCT SIZE



63.0MM



75MM

52MM

